Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.003”**

**.003”**

**.022”**

**.022”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .003” X .003”**

**Backside Potential: Cathode**

**Mask Ref: TNL**

**APPROVED BY: DK DIE SIZE .022” X .022” DATE: 9/7/21**

**MFG: ALLEGRO/SPRAGUE THICKNESS .008” P/N: 2N2218**

**DG 10.1.2**

#### Rev B, 7/19/02